A Manual on use of DESTINY Tool for Architectural Studies

Abstract

DESTINY is a tool for modeling 3D caches designed with SRAM, eDRAM, STT-RAM, PCM and ReRAM [1, 2]. This manual explains some of the internals and parameters of DESTINY. It shows a typical configuration file and the corresponding output, which may be especially useful for a user who wants to get an overview of DESTINY even before installing it. This manual also provides ideas and suggestions for integrating DESTINY into architectural simulators and points towards future work.

This manual is expected to be useful for researchers to assess the scope and potential of DESTINY and help them in using DESTINY to drive architectural studies. This manual is also expected to answer some of the "frequently asked questions" related to DESTINY.

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I. INTEGRATING DESTINY INTO AN ARCHITECTURAL SIMULATOR

Note that DESTINY is NOT a timing simulator like Sniper, GEM5, SimpleScalar, MARSS etc. Rather, DESTINY is analogous to CACTI, NVSim etc. DESTINY provides area, timing and energy parameters for the cache.

There are at least three ways of integrating DESTINY into architectural simulators.

- 1) The code of DESTINY can be interfaced directly with that of a simulator. The inputs which are generally given to DESTINY as .cfg file can instead be passed through suitable function calls. Although this option allows highest flexibility, it is likely to be difficult and time-consuming.
- 2) DESTINY can be integrated in a tool like McPAT to model caches.
- 3) By separately running DESTINY code, the required parameters can be found, which be stored in a file. Later on, the simulator can read these values as a lookup table and use them for timing simulation. The energy values can be computed, for example, by multiplying number of reads/writes with corresponding read/write access energy values. This is a simple option, but does not allow as much flexibility as the previous options.

Note that DESTINY only models cache energy and to model the energy consumption of other components such as main memory and core, other tools may be required.

A. Accounting for read-write asymmetric memories

Non-volatile memories such as STT-RAM, ReRAM and PCM have different latencies and access energy values for reads and writes. For such memories, due care needs to be taken while using DESTINY output in an architectural simulator, since the values for read and write need to be separately replaced.

II. ILLUSTRATION OF TYPICAL INPUT AND OUTPUT OF DESTINY

The first Listing below shows a typical input configuration file for DESTINY and the second Listing below shows the output of DESTINY for this configuration file.

Listing 1: Configuration (input) file for a 3D ReRAM cache

```
-DesignTarget: cache
  -ProcessNode: 32
  -Capacity (MB): 16
  -WordWidth (bit): 512
  -Associativity (for cache only): 16
  -PrintLevel: 1
  -DeviceRoadmap: HP
  -LocalWireType: LocalConservative
  -LocalWireRepeaterType: RepeatedNone
  -LocalWireUseLowSwing: No
  -GlobalWireType: GlobalConservative
  -GlobalWireRepeaterType: RepeatedNone
  -GlobalWireUseLowSwing: No
  -Routing: H-tree
  //-Routing: Non-H-tree
//-InternalSensing: false
  -MemoryCellInputFile: sample RRAM.cell
  -Temperature (K): 350
  //-OptimizationTarget: WriteLatency
  //-OptimizationTarget: Full
```

```
-OptimizationTarget: WriteEDP

-BufferDesignOptimization: balanced

//- ForceBankA (Total AxB): 64x128
//- ForceBank (Total AxB, Active CxD): 8x16x4, 8x4

//- ForceMatA (Total AxB): 1x1
//- ForceMat (Total AxB, Active CxD): 2x2, 1x2

//- ForceMuxSenseAmp: 32
//- ForceMuxOutputLev1: 1
//- ForceMuxOutputLev2: 1

-StackedDieCount: 2
-MonolithicStackCount: 1
```

Listing 2: Parameters (output) obtained from DESTINY for above configuration file

```
User-defined configuration file (Input_3DReRAM.cfg) is loaded
  ______
  DESIGN SPECIFICATION
  _____
  Design Target: Cache
  Capacity: 16MB
  Cache Line Size: 64Bytes
  Cache Associativity: 16 Ways
  Searching for the best solution that is optimized for write energy-delay-product ...
  Using cell file: sample RRAM.cell
  numSolutions = 123506 / numDesigns = 15604974
  ______
  CACHE DESIGN — SUMMARY
  _____
  Access Mode: Normal
18 Area:
  - Total Area = 2.195mm<sup>2</sup>
  |--- Data Array Area = 946.864um x 539.400um = 1.913mm^2
   |--- Tag Array Area = 477.882um x 379.131um = 0.282mm^2
22 Timing:

    Cache Hit Latency

                       = 11.692 ns
  - Cache Miss Latency = 2.028ns

    Cache Write Latency = 14.650ns

26 Power:

    Cache Hit Dynamic Energy

                               = 0.445nJ per access
  - Cache Miss Dynamic Energy = 0.445nJ per access
   - Cache Write Dynamic Energy = 0.164nJ per access
  - Cache Total Leakage Power = 135.741mW
   |--- Cache Data Array Leakage Power = 57.675mW
  |--- Cache Tag Array Leakage Power = 78.066mW
32
 CACHE DATA ARRAY DETAILS
34
     _____
        SUMMARY
36
     ==========
      Optimized for: Write Energy-Delay-Product
38
     Memory Cell: RRAM (Memristor)
      Cell Area (F<sup>2</sup>)
                       : 4.000 (2.000Fx2.000F)
40
      Cell Aspect Ratio : 1.000
      Cell Turned-On Resistance : 1.000Mohm
42
      Cell Turned-Off Resistance: 10.000Mohm
      Read Mode: Current-Sensing
44
       - Read Voltage: 0.300V
      Reset Mode: Voltage
46
```

```
- Reset Voltage: 2.000V
        - Reset Pulse: 4.000ns
48
       Set Mode: Voltage
        - Set Voltage: 2.000V
50
        - Set Pulse: 4.000ns
       Access Type: Diode
52
54
      CONFIGURATION
       _____
56
      Bank Organization: 4 x 1 x 2
       - Row Activation : 2 / 4 x 1
58
       - Column Activation: 1 / 1 x 1
      Mat Organization: 2 x 2
60
       - Row Activation : 2 / 2
       - Column Activation: 2 / 2
62
       - Subarray Size : 1024 Rows x 4096 Columns
      Mux Level:

    Senseamp Mux

       - Output Level-1 Mux: 1
       - Output Level-2 Mux: 1
       - One set is partitioned into 1 rows
       Local Wire:
                           Local Conservative
       - Wire Type :
70
       - Repeater Type:
                             No Repeaters
       - Low Swing:
       Global Wire:
       - Wire Type :
                           Global Conservative
       - Repeater Type:
                           No Repeaters
       - Low Swing:
76
       Buffer Design Style:
                                 Balanced
      ==========
78
         RESULT
      ==========
80
      Area:
       - Total Area = 946.864um x 539.400um = 1.913mm<sup>2</sup>
82
                           = 236.716um x 539.400um = 127684.538um^2
                                                                         (107.639\%)
       |--- Mat Area
       |--- Subarray Area = 118.358um x 265.604um = 31436.314um^2
                                                                        (109.300\%)
84
       |--- TSV Area
                           = 900.000 \text{um}^2
        Area Efficiency = 28.739%
86
      Timing:
       - Read Latency = 6.766ns
88
       |--- TSV Latency = 0.010ps
        |--- H-Tree Latency = 50.185ps
        |--- Mat Latency
                          = 6.715 \, \text{ns}
           |--- Predecoder Latency = 84.055ps
92
           |--- Subarray Latency = 6.631ns
              |--- Row Decoder Latency = 5.421ns
              --- Bitline Latency
                                        = 115.197 \, ps
              |--- Senseamp Latency
                                        = 1.073 \, \text{ns}
              --- Mux Latency
                                        = 22.311 ps
              |--- Precharge Latency
                                        = 525.993 \, ps
98
       - Write Latency = 14.650ns
       |--- TSV Latency
                          = 0.005 \, ps
100
        |--- H-Tree Latency = 25.093ps
       |--- Mat Latency = 14.625ns
102
          |--- Predecoder Latency = 84.055ps
           |--- Subarray Latency = 14.541ns
104
              |--- Row Decoder Latency = 5.421ns
              |--- Charge Latency
                                        = 807.650 \, ps
106
       - Read Bandwidth = 36.864GB/s
       - Write Bandwidth = 4.401GB/s
108
       Power:
```

64

68

94

96

```
|--- TSV Dynamic Energy = 29.955pJ
        |--- H-Tree Dynamic Energy = 52.428pJ
112
       |--- Mat Dynamic Energy = 147.443pJ per mat
          |--- Predecoder Dynamic Energy = 0.238pJ
114
           |--- Subarray Dynamic Energy = 36.801pJ per active subarray
              |--- Row Decoder Dynamic Energy = 0.397pJ
116
              --- Mux Decoder Dynamic Energy = 0.792pJ
              --- Bitline & Cell Read Energy = -0.185pJ
118
              --- Senseamp Dynamic Energy
                                               = 32.337 pJ
              --- Mux Dynamic Energy
                                               = 0.529 pJ
120
              |--- Precharge Dynamic Energy
                                               = 2.930 \, pJ
       - Write Dynamic Energy = 135.726pJ
       --- TSV Dynamic Energy
                                 = 29.955 pJ
        |--- H-Tree Dynamic Energy = 52.428pJ
       |--- Mat Dynamic Energy = 26.671pJ per mat
          |--- Predecoder Dynamic Energy = 0.238pJ
126
           |--- Subarray Dynamic Energy = 6.608pJ per active subarray
              |--- Row Decoder Dynamic Energy = 0.397pJ
128
              |--- Mux Decoder Dynamic Energy = 0.792pJ
              |--- Mux Dynamic Energy
                                               = 0.529 pJ
130
       Leakage Power = 57.675mW
       |--- TSV Leakage
                                       = 0.000 \text{pW}
       |--- H-Tree Leakage Power
                                      = 0.000 pW
       |--- Mat Leakage Power
                                      = 7.209 \text{mW per mat}
134
  CACHE TAG ARRAY DETAILS
136
      _____
         SUMMARY
138
      =========
      Optimized for: Write Energy-Delay-Product
140
      Memory Cell: RRAM (Memristor)
      Cell Area (F<sup>2</sup>)
                         : 4.000 (2.000Fx2.000F)
140
       Cell Aspect Ratio : 1.000
       Cell Turned-On Resistance: 1.000Mohm
144
       Cell Turned-Off Resistance: 10.000Mohm
      Read Mode: Current-Sensing
146
        - Read Voltage: 0.300V
      Reset Mode: Voltage
148
        - Reset Voltage: 2.000V
150
        - Reset Pulse: 4.000ns
      Set Mode: Voltage
        - Set Voltage: 2.000V
152
        - Set Pulse: 4.000ns
      Access Type: Diode
154
156
      =========
      CONFIGURATION
      =========
158
      Bank Organization: 2 x 1 x 2
       - Row Activation : 1 / 2 x 1
160
       - Column Activation: 1 / 1 x 1
      Mat Organization: 2 x 2
162
       - Row Activation
                         : 2 / 2
       - Column Activation: 1 / 2
164

    Subarray Size

                         : 256 Rows x 1920 Columns
      Mux Level:
166
       - Senseamp Mux
                          : 8
       - Output Level-1 Mux: 1
168
       - Output Level-2 Mux: 1
       - One set is partitioned into 1 rows
      Local Wire:
172
       - Wire Type :
                        Local Aggressive
```

Read Dynamic Energy = 377.269pJ

110

```
- Repeater Type:
                              No Repeaters
        - Low Swing:
174
       Global Wire:
       - Wire Type :
                           Global Aggressive
176
       - Repeater Type:
                             No Repeaters
        - Low Swing:
                           Yes
178
       Buffer Design Style:
                                 Latency-Optimized
       =========
180
         RESULT
       =========
182
       Area:
        - Total Area = 477.882um x 379.131um = 281979.865um^2
184
        |--- Mat Area
                           = 238.941um x 379.131um = 90589.933um<sup>2</sup>
                                                                         (17.779\%)
        |-- Subarray Area = 119.180um x 184.128um = 21944.375um<sup>2</sup>
                                                                         (18.349\%)
186
        |--- TSV Area
                        = 900.000 \text{um}^2
        - Area Efficiency = 11.424%
188
       Timing:
        Read Latency = 2.028ns
190
        |--- TSV Latency = 0.010 \,\mathrm{ps}
        |--- H-Tree Latency = 379.767ps
192
        |--- Mat Latency = 1.648ns
           |--- Predecoder Latency = 98.405ps
194
           |--- Subarray Latency = 1.526ns
              |--- Row Decoder Latency = 436.013 \, ps
190
              |--- Bitline Latency
                                        = 5.708 ps
              |--- Senseamp Latency
                                        = 1.073 \, \text{ns}
198
              |--- Mux Latency
                                        = 11.370 ps
              |--- Precharge Latency = 121.199ps
200
           |--- Comparator Latency = 24.237ps
        – Write Latency = 8.787ns
202
        |--- TSV Latency
                          = 0.005 \, ps
        |--- H-Tree Latency = 189.883ps
204
        |--- Mat Latency
                           = 8.597 ns
           |--- Predecoder Latency = 98.405ps
206
           |--- Subarray Latency = 8.499ns
              |--- Row Decoder Latency = 436.013 \, ps
              |--- Charge Latency
                                        = 62.965 ps
        - Read Bandwidth = 3.097GB/s
        – Write Bandwidth = 441.230MB/s
       Power:

    Read Dynamic Energy = 68.054pJ

        |--- TSV Dynamic Energy = 2.540 \,\mathrm{pJ}
214
        |--- H-Tree Dynamic Energy = 0.581pJ
        |--- Mat Dynamic Energy = 64.933pJ per mat
216
           |--- Predecoder Dynamic Energy = 1.032pJ
           |--- Subarray Dynamic Energy = 31.950pJ per active subarray
218
              |--- Row Decoder Dynamic Energy = 0.208pJ
              |--- Mux Decoder Dynamic Energy = 0.435pJ
220
               --- Bitline & Cell Read Energy = -0.695pJ
               --- Senseamp Dynamic Energy
                                                = 30.316 pJ
               --- Mux Dynamic Energy
                                                = 0.302 pJ
              |--- Precharge Dynamic Energy
                                                = 1.384 \, pJ

    Write Dynamic Energy = 28.312pJ

        --- TSV Dynamic Energy
                                  = 2.540 \, pJ
226
        |--- H-Tree Dynamic Energy = 0.581pJ
        |--- Mat Dynamic Energy = 25.191pJ per mat
228
           |--- Predecoder Dynamic Energy = 1.032pJ
           |--- Subarray Dynamic Energy = 12.079pJ per active subarray
230
              |--- Row Decoder Dynamic Energy = 0.208pJ
              |--- Mux Decoder Dynamic Energy = 0.435pJ
              --- Mux Dynamic Energy
                                                = 0.302 pJ
        Leakage Power = 78.066mW
234
        |--- TSV Leakage
                                       Wq000.0
```

A. Understanding DESTINY output

Listing 2 above provides the detailed output. It first provides the summary for whole cache and then its individual breakdown for data array and tag array, respectively. Listing 3 below shows the selected output from Listing 2. Most researchers who don't want to worry about breakdown of results into tag/array will just be interested in the results shown in Listing 3.

Listing 3: Selected output from Listing 2

```
_____
CACHE DESIGN — SUMMARY
_____
Access Mode: Normal
Area:
- Total Area = 2.195mm<sup>2</sup>
Timing:

    Cache Hit Latency

                      = 11.692ns
  Cache Miss Latency = 2.028ns
- Cache Write Latency = 14.650ns
Power:
- Cache Hit Dynamic Energy
                             = 0.445nJ per access
  Cache Miss Dynamic Energy = 0.445nJ per access
  Cache Write Dynamic Energy = 0.164nJ per access
  Cache Total Leakage Power
                            = 135.741 \text{mW}
```

To use timing parameters of DESTINY, note that in sequetial cache access mode, we have

```
Cache Hit Latency = Tag lookup latency + data read access latency

Cache Miss Latency = Tag lookup latency

Cache Write Latency = Tag lookup latency + data write access latency

(3)
```

III.USE OF DESTINY TO MODEL ASSIST STRUCTURES

DESTINY is useful to model not only the regular caches, but 'assist structures' also. For example, some works use profiling cache [3, 4], victim cache [5], write buffer etc. These additional structures are typically small-sized and are useful for some profiling work, prediction work (e.g. dead-block prediction), keeping the evicted blocks, etc. These structures are used as part of a broader architectural technique which may be proposed to improve cache lifetime, performance, energy etc. To comprehensively account for the overhead of that technique, it is important to account for area, timing and energy overhead of these assist structures.

By either modifying the DESTINY code suitably or by specifying their parameters as such, a user may be able to model these structures in DESTINY. Also, DESTINY provides separate parameters for tag and data arrays and this is userful for gaining more insight and seeing the fractional contribution of both arrays.

IV. ADVANTAGE OF COMPREHENSIVENESS OF DESTINY

Study and comparison of different memory technologies (e.g. SRAM, NVMs) is desirable for finding the most suitable one for a given workload or usage scenario. In absence of a comprehensive modeling tool that can model all memory technologies simultanesouly, researchers have different tools for modeling them, for example, CACTI for

modeling SRAM and NVSim for modeling NVMs and in-house tools for modeling eDRAM etc. (e.g. [6]). However, there are several challenges and pitfalls in such an approach:

- Different tools have different modeling assumptions, output format and even different output values for same input configuration [1].
- Over time, these tools undergo revisions (due to more accurate modeling, bug fixes and other improvements), and in such a case, their cross-comparison becomes difficult.
- Use of in-house tools precludes reproducing the results.

Due to these factors, the conclusions derived from these studies may be inaccurate and misleading.

By comparison, DESTINY is a comprehensive tool which can model 5 memory technologies (and we plan to include other memory technologies soon). This allows meaningful comparison and a single code-base for improvement. It also reduces the effort on part of researchers/users to configure the tool properly.

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